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(12) **United States Design Patent**
Okada et al.

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(54) **HEAT DISSIPATION DETERRENCE LINK FOR SEMICONDUCTOR MANUFACTURE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

Jun. 16, 2006 (JP) 2006-015664

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
D8/16; D23/386; 118/724, 725; 432/241,
432/242; 438/680

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heat dissipation deterrence link for semiconductor manufacture, as shown and described.

DESCRIPTION

FIG. 1 is a front view of the design for a in accordance with the invention;

FIG. 2 is a rear view thereof;

FIG. 3 is a right side view thereof;

FIG. 4 is a left side view thereof;

FIG. 5 is a plan view thereof;

FIG. 6 is a bottom view thereof;

FIG. 7 is a sectional view thereof along 7—7 of FIG. 1;

FIG. 8 is a perspective view thereof; and,

FIG. 9 shows a heat dissipation deterrence link for semiconductor manufacture in accordance with the invention in use.

The dash lines indicate the boundary of the claimed design and form no part of the claimed design.

1 Claim, 5 Drawing Sheets

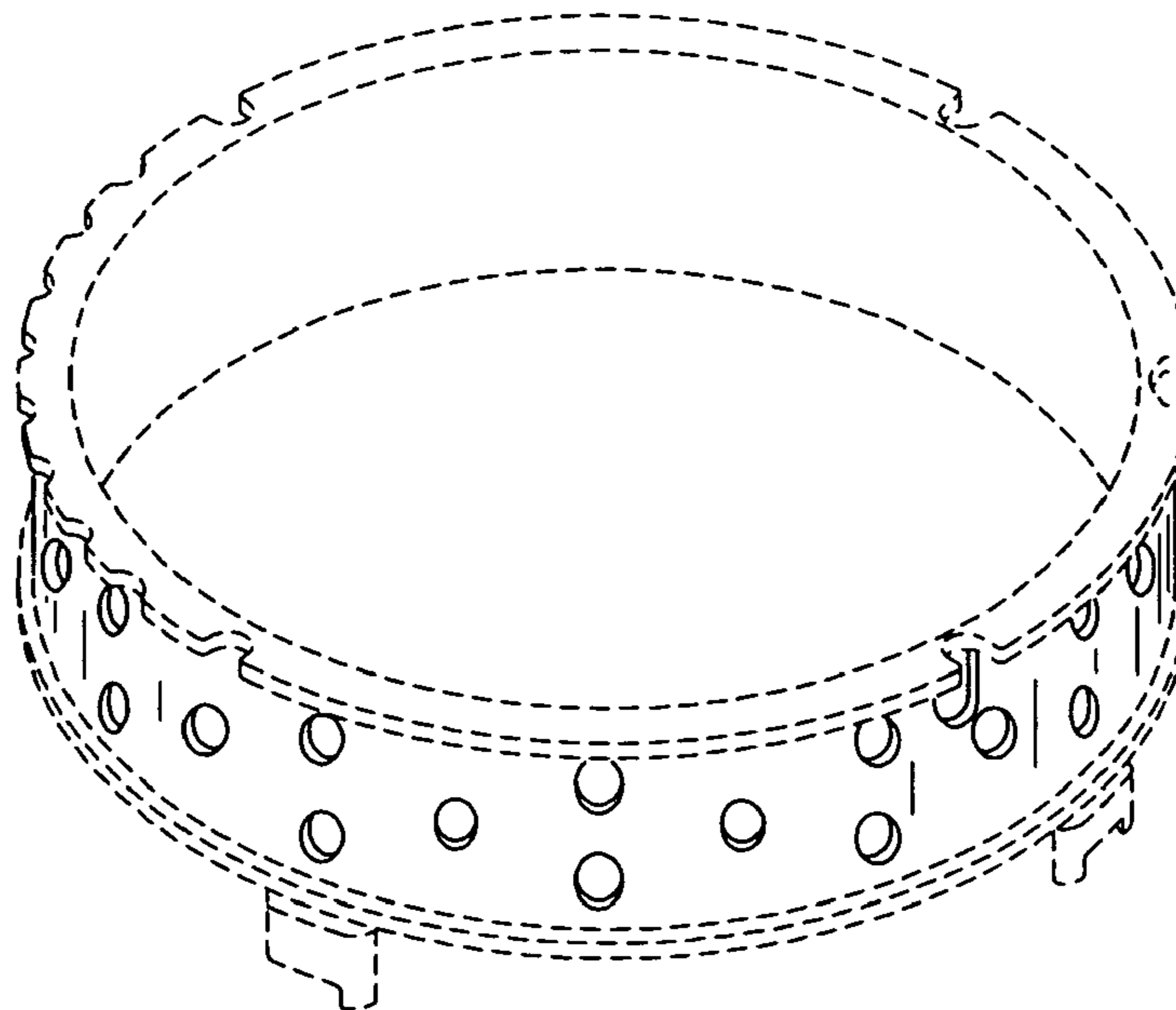


FIG. 1

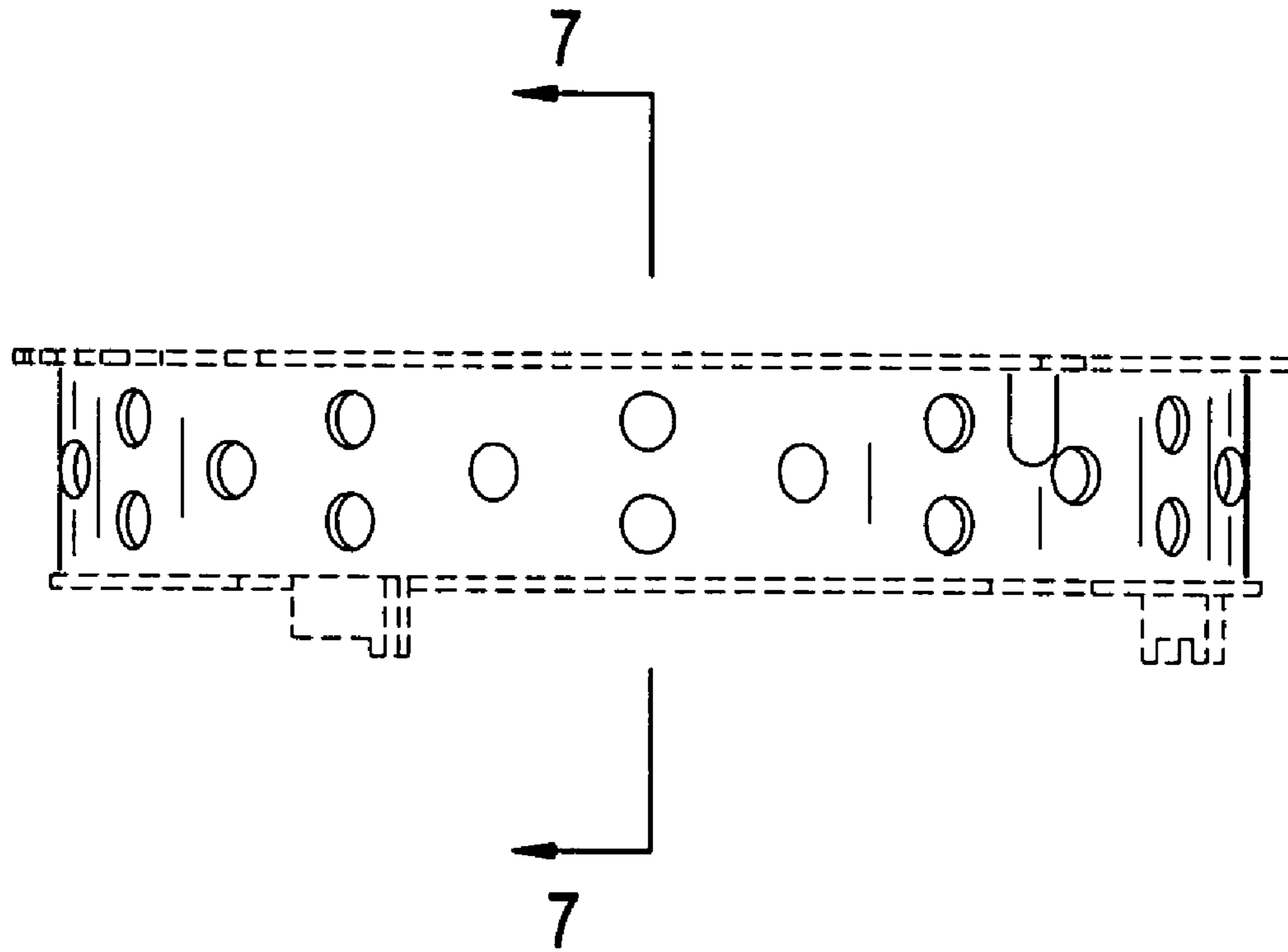


FIG. 2

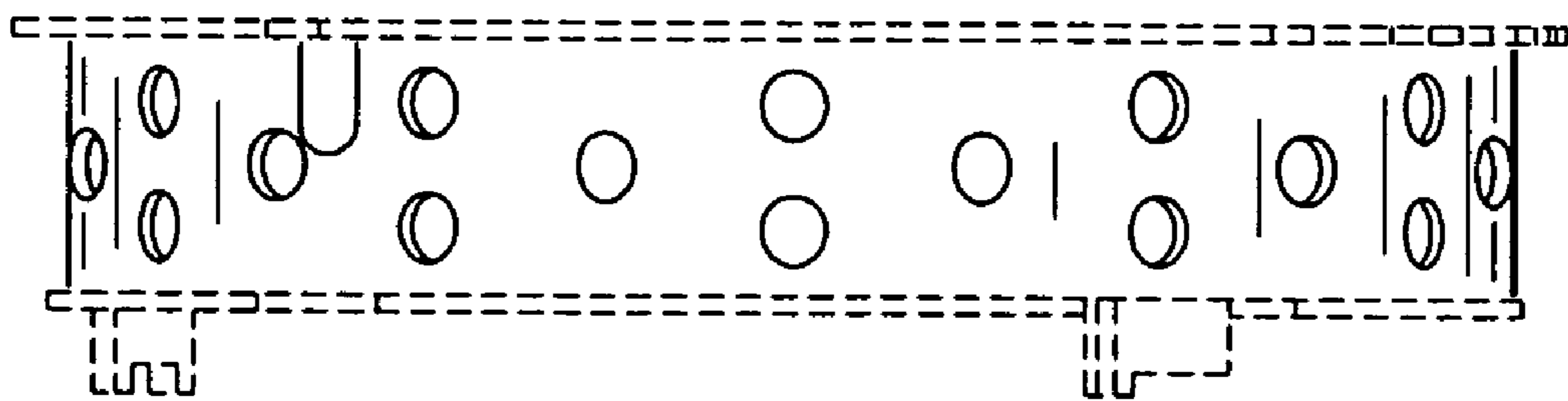


FIG. 3

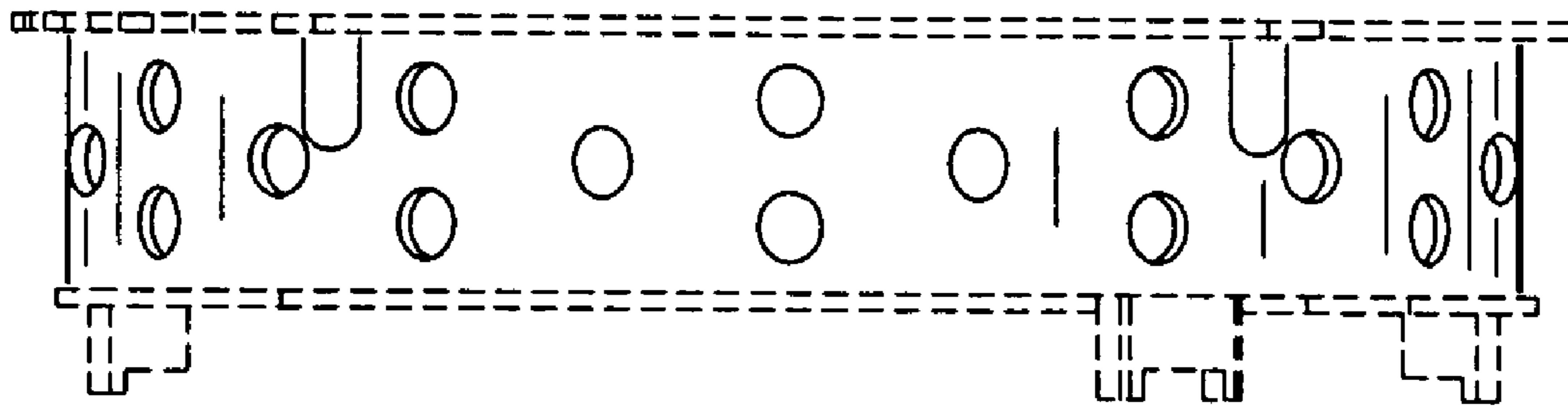


FIG. 4

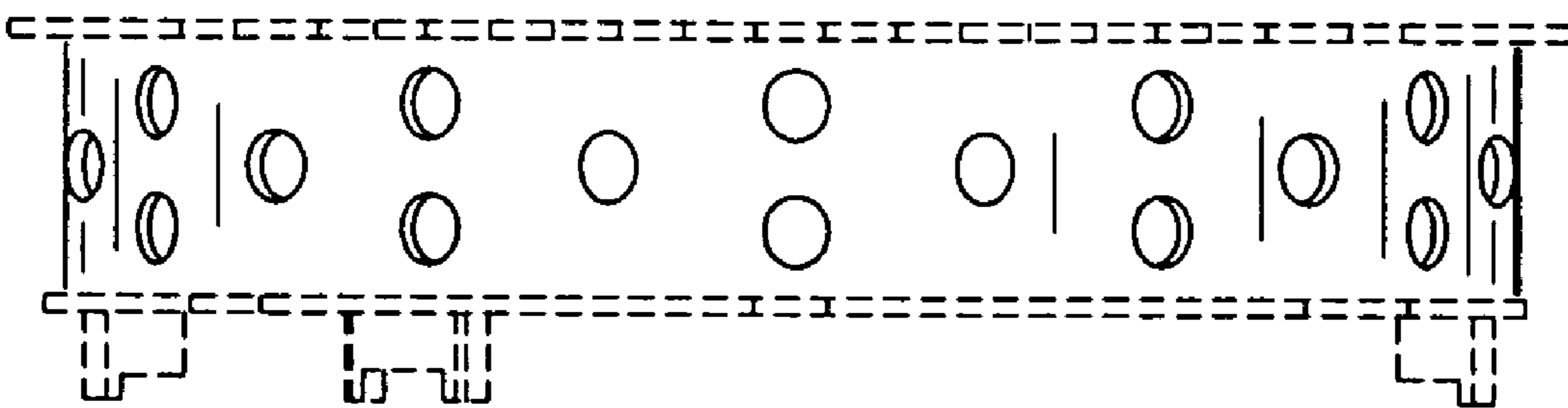


FIG. 5

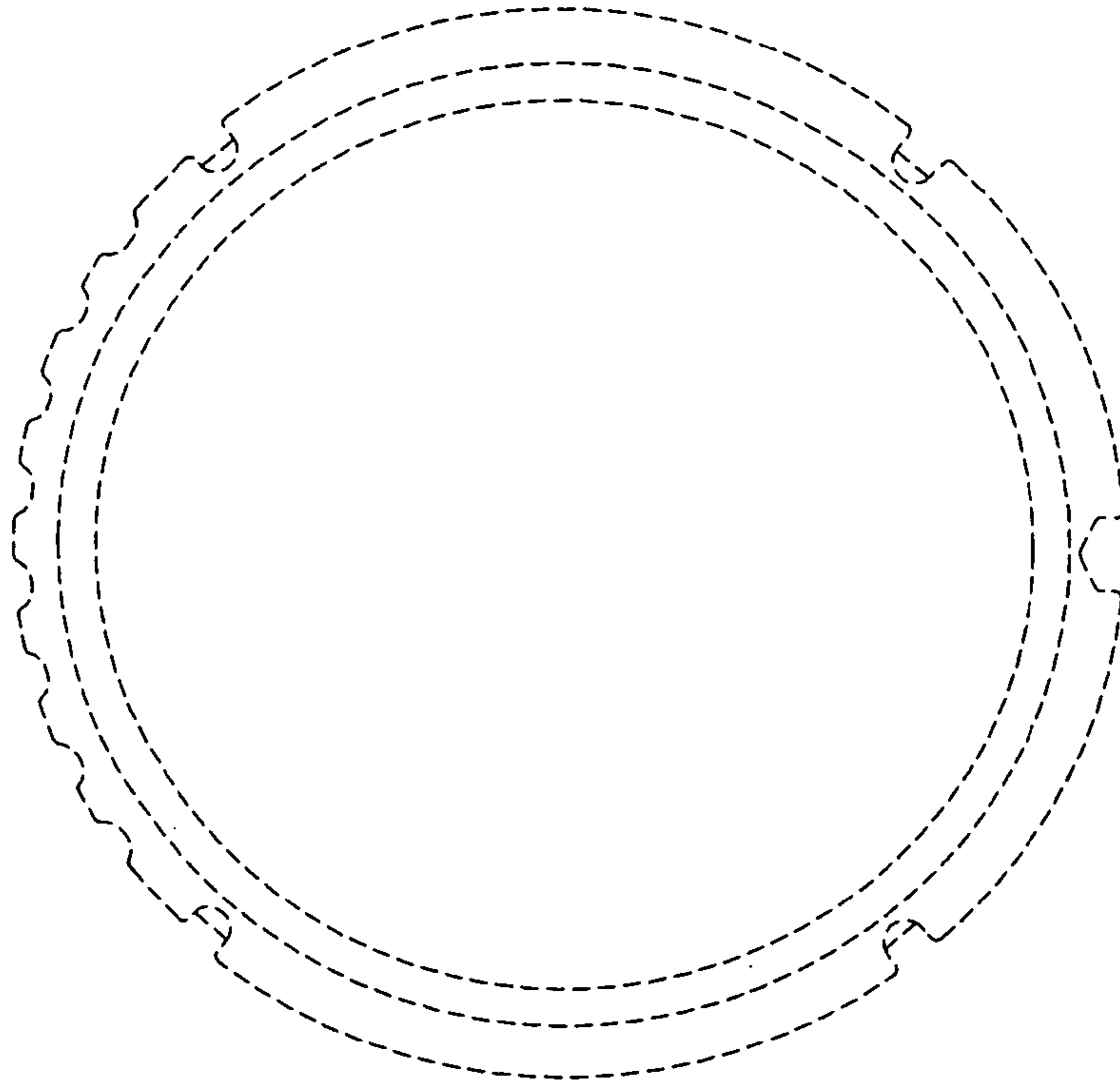


FIG. 6

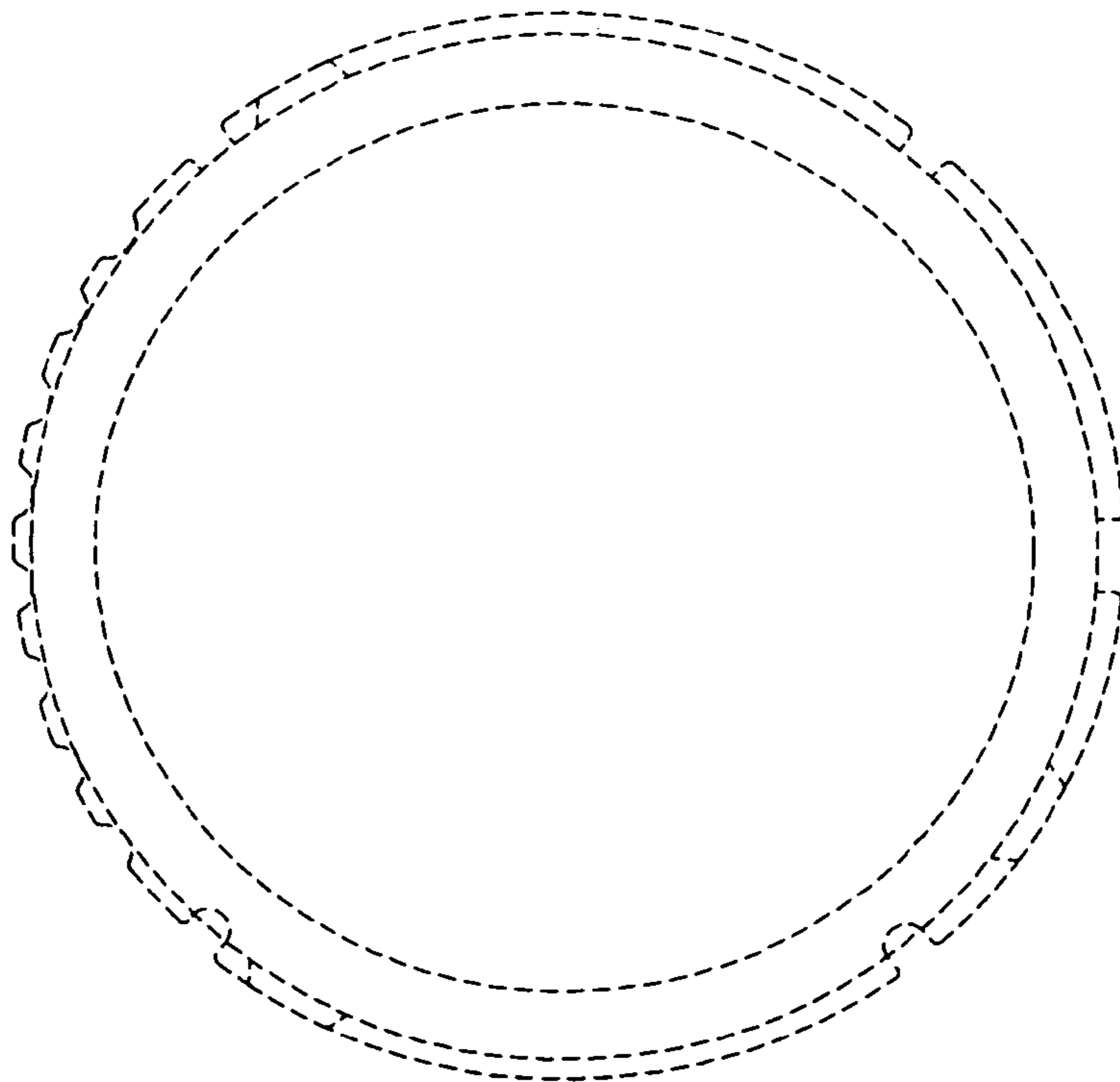


FIG. 7

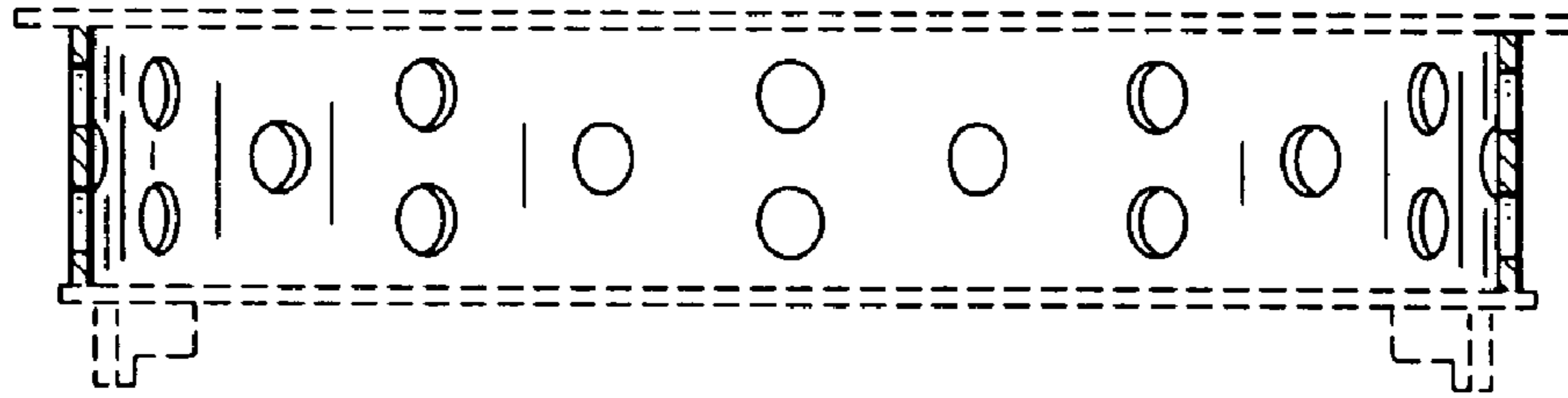


FIG. 8

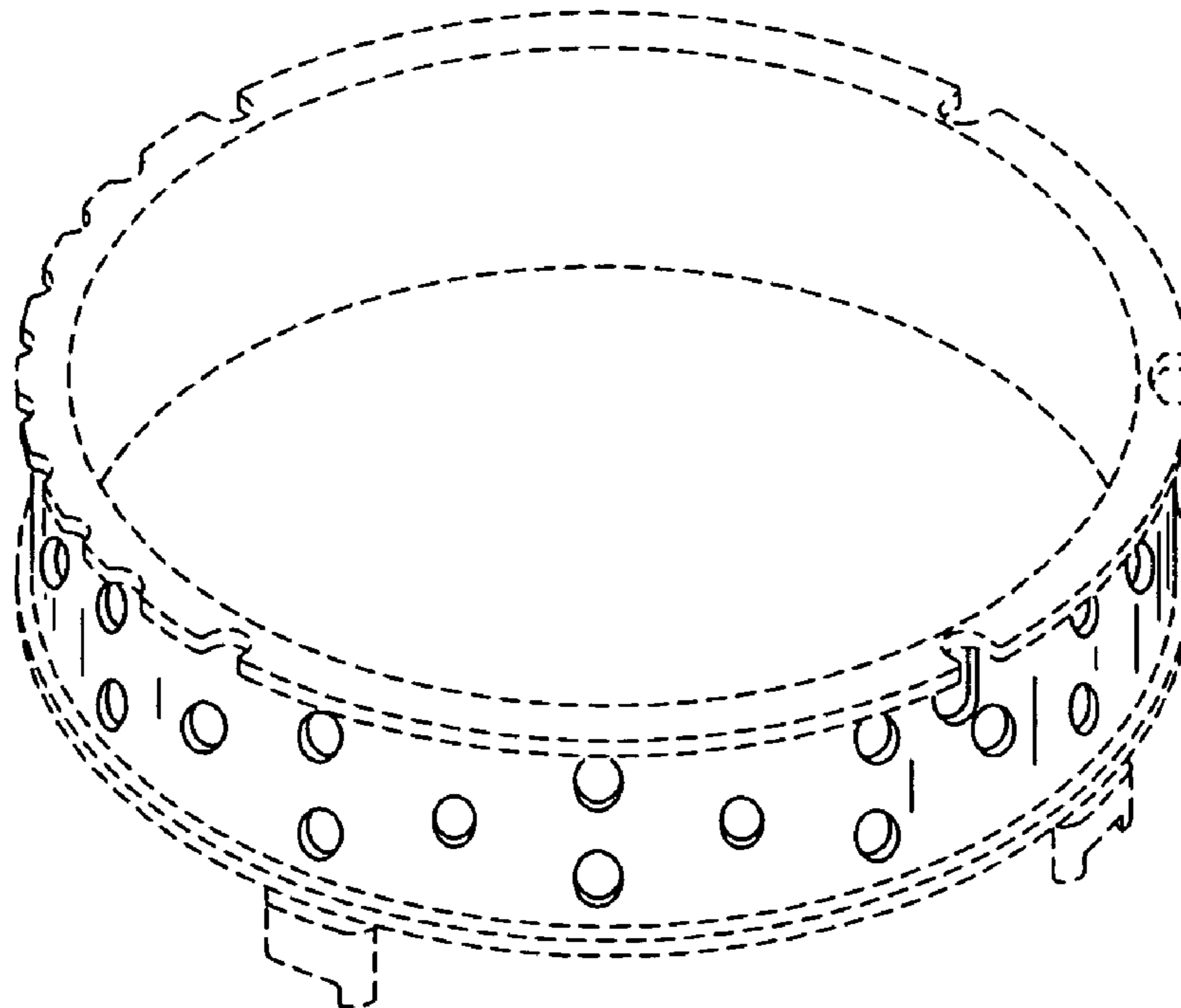


FIG. 9

